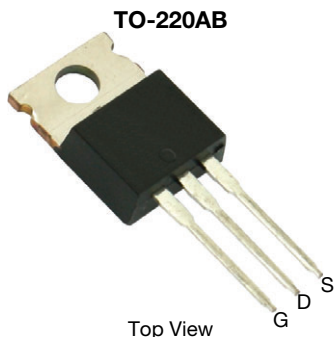


N-Channel 80 V (D-S) MOSFET



FEATURES

- TrenchFET® power MOSFET
- Maximum 175 °C junction temperature
- Very low Q_{gd} reduces power loss from passing through $V_{plateau}$
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Power supply
- Secondary synchronous rectification
- DC/DC converter
- Power tools
- Motor drive switch
- DC/AC inverter
- Battery management
- OR-ing / e-fuse



N-Channel MOSFET

PRODUCT SUMMARY

V_{DS} (V)	80
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.0024
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5$ V	0.0028
Q_g typ. (nC)	151.2
I_D (A)	150 ^d
Configuration	Single

ORDERING INFORMATION

Package	TO-220
Lead (Pb)-free and halogen-free	SUP60020E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	80	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current ($T_J = 150$ °C)	I_D	150 ^d	A
		150 ^d	
Pulsed drain current ($t = 100$ μ s)	I_{DM}	500	A
Avalanche current	I_{AS}	60	A
Single avalanche energy ^a	E_{AS}	180	mJ
Maximum power dissipation ^a	P_D	375 ^b	W
		125 ^b	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-ambient (PCB mount) ^c	R_{thJA}	40	°C/W
Junction-to-case (drain)	R_{thJC}	0.4	°C/W

Notes

- Duty cycle ≤ 1 %
- See SOA curve for voltage derating
- When mounted on 1" square PCB (FR4 material)
- Package limited



SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	80	-	-	V
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2	-	4	
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 250	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 125 °C	-	-	150	
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 175 °C	-	-	5	mA
On-state drain current ^a	I _{D(on)}	V _{DS} ≥ 10 V, V _{GS} = 10 V	120	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 30 A	-	0.00200	0.00240	Ω
		V _{GS} = 7.5 V, I _D = 20 A	-	0.00215	0.00280	
Forward transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 30 A	-	115	-	S
Dynamic ^b						
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 40 V, f = 1 MHz	-	10 680	-	pF
Output capacitance	C _{oss}		-	1180	-	
Reverse transfer capacitance	C _{rss}		-	50	-	
Total gate charge ^c	Q _g	V _{DS} = 40 V, V _{GS} = 10 V, I _D = 41.7 A	-	151.2	227	nC
Gate-source charge ^c	Q _{gs}		-	48.4	-	
Gate-drain charge ^c	Q _{gd}		-	24	-	
Output charge	Q _{oss}	V _{DS} = 40 V, V _{GS} = 0 V	-	138	207	
Gate resistance	R _g	f = 1 MHz	0.34	1.7	3.4	Ω
Turn-on delay time ^c	t _{d(on)}	V _{DD} = 40 V, R _L = 1.2 Ω I _D ≅ 33.3 A, V _{GEN} = 10 V, R _g = 1 Ω	-	30	60	ns
Rise time ^c	t _r		-	13	26	
Turn-off delay time ^c	t _{d(off)}		-	50	100	
Fall time ^c	t _f		-	15	30	
Drain-Source Body Diode Ratings and Characteristics ^b (T _C = 25 °C)						
Pulsed current (t = 100 μs)	I _{SM}		-	-	250	A
Forward voltage ^a	V _{SD}	I _F = 10 A, V _{GS} = 0 V	-	0.75	1.5	V
Reverse recovery time	t _{rr}	I _F = 33.3 A, di/dt = 100 A/μs	-	80	160	ns
Peak reverse recovery charge	I _{RM(REC)}		-	4	6	A
Reverse recovery charge	Q _{rr}		-	0.182	0.275	μC
Reverse recovery fall time	t _a		-	44	-	ns
Reverse recovery rise time	t _b		-	36	-	

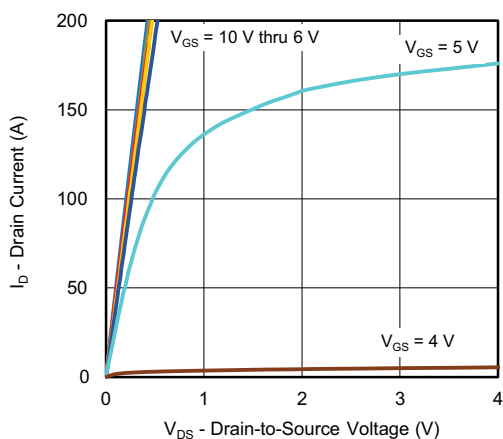
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing
c. Independent of operating temperature

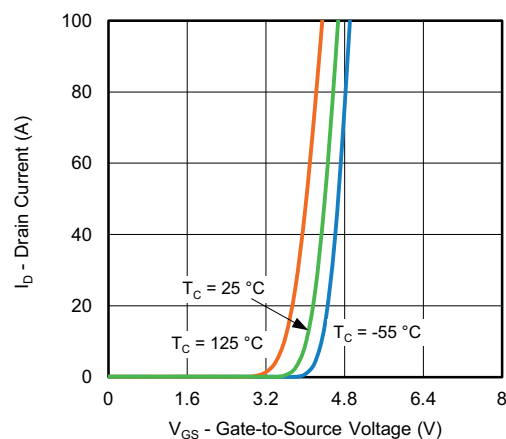
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



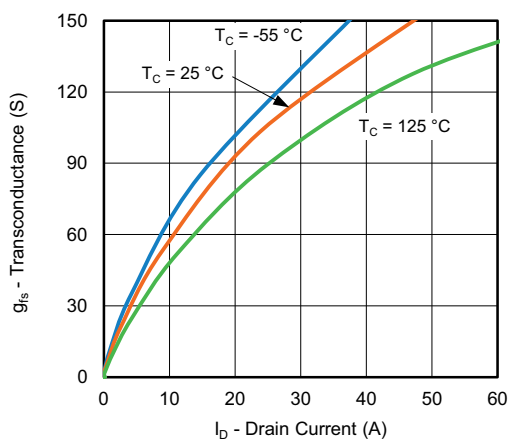
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



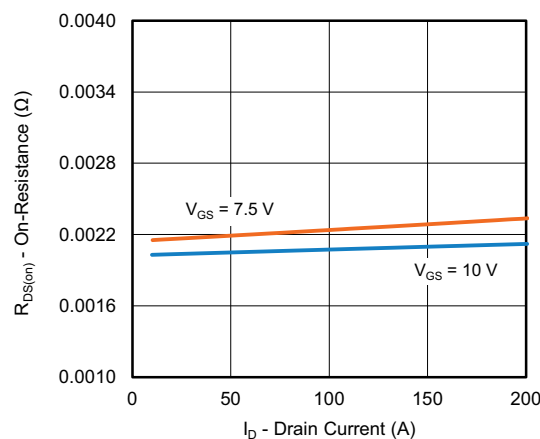
Output Characteristics



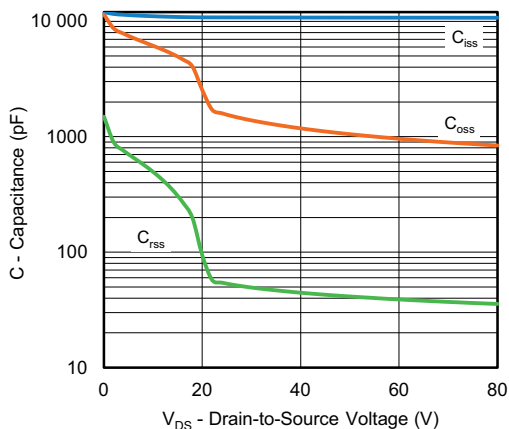
Transfer Characteristics



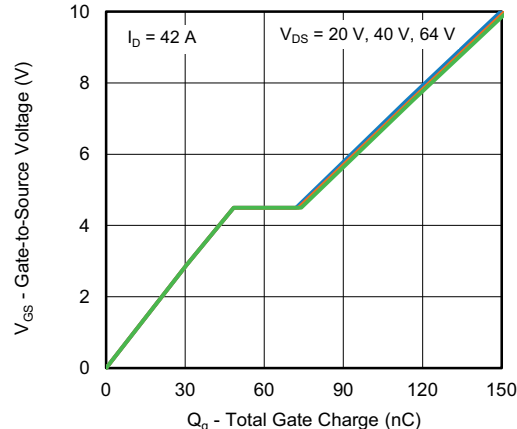
Transconductance



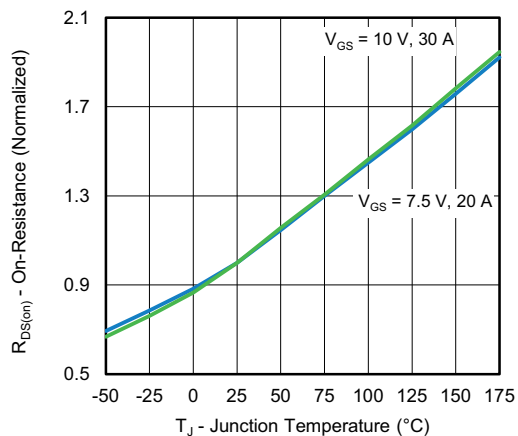
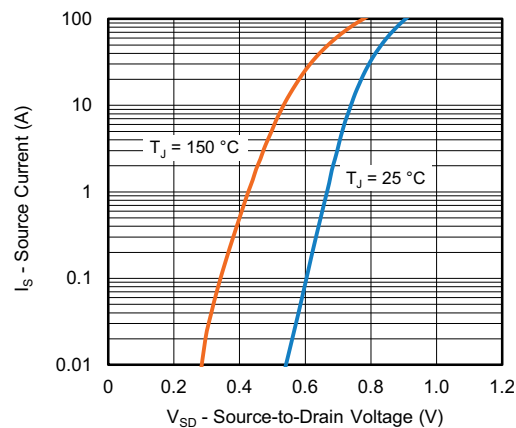
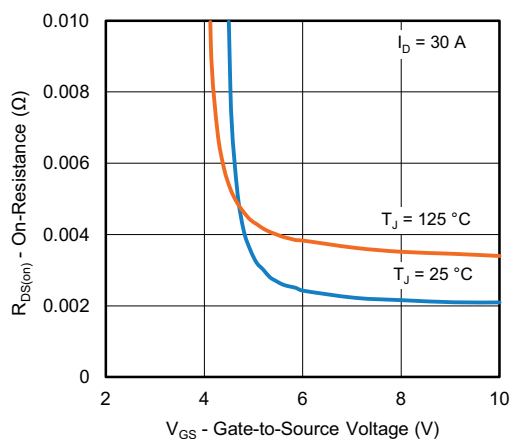
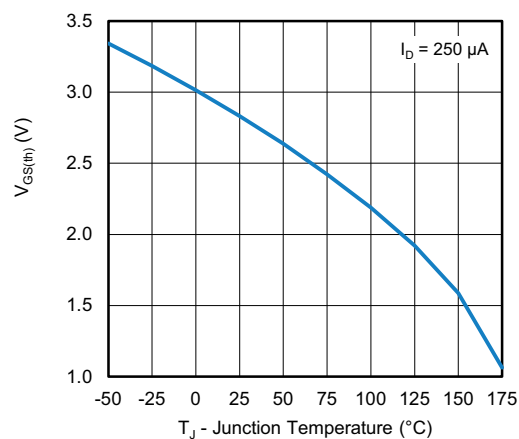
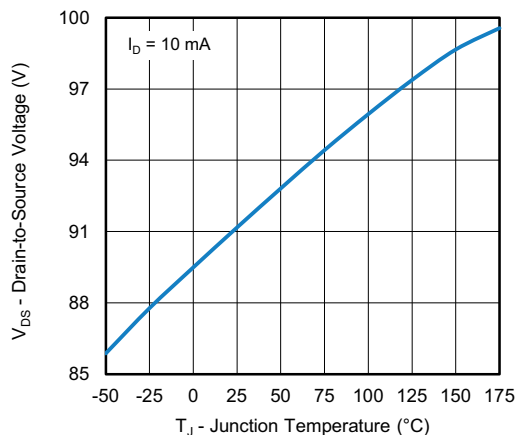
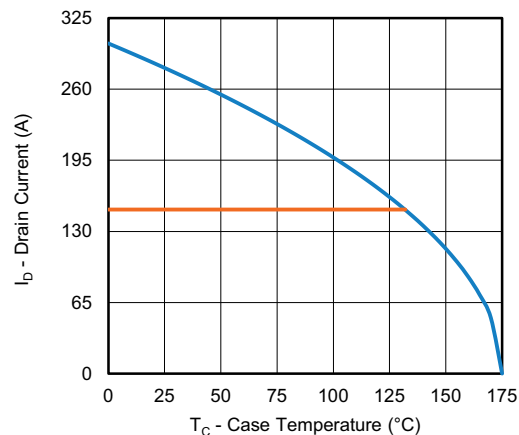
On-Resistance vs. Drain Current



Capacitance

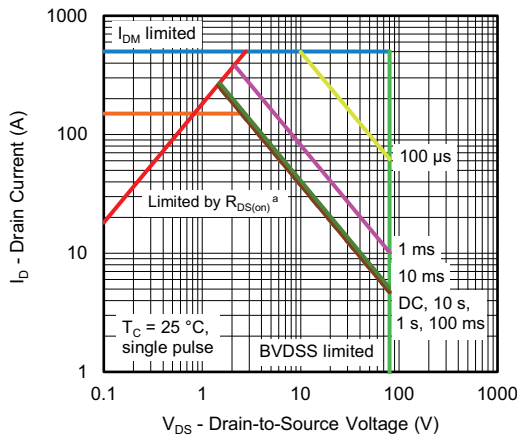


Gate Charge

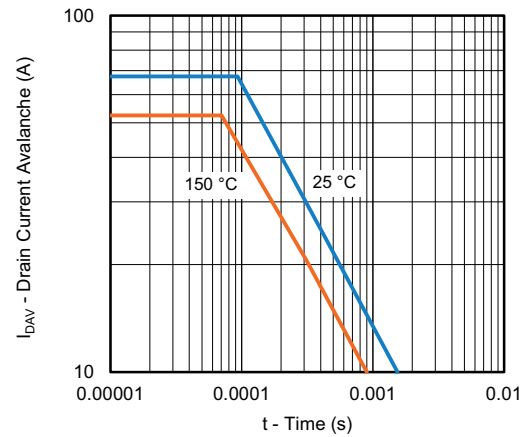
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

On-Resistance vs. Junction Temperature

Source Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage

Drain Source Breakdown vs. Junction Temperature

Current De-rating



THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



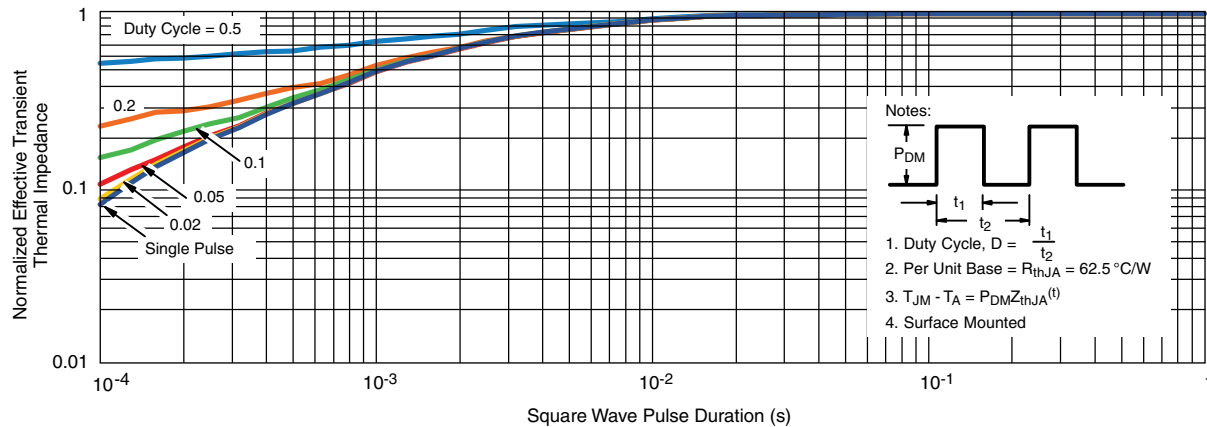
Safe Operating Area



Single Pulse Avalanche Current Capability vs. Time

Note

- a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction to Ambient (25 $^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction to Case (25 $^{\circ}\text{C}$)
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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TO-220AB



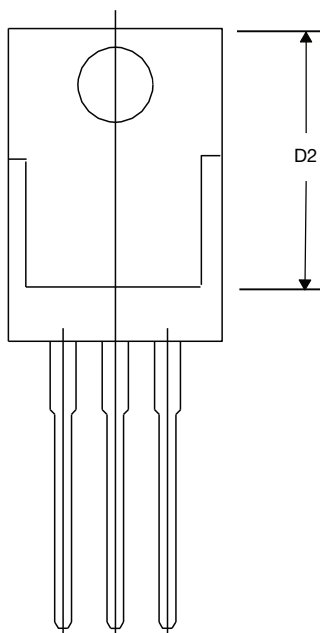
DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
$\varnothing P$	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

ECN: T14-0413-Rev. P, 16-Jun-14

DWG: 5471

Note

* $M = 1.32$ mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM





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